



**SLOVENSKI STANDARD**  
**SIST-TP CLC/TR 62258-4:2008**  
**01-januar-2008**

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Standardizacijski inštitut Slovenije  
SIST-TP CLC/TR 62258-4:2008

Semiconductor die products - Part 4: Questionnaire for die users and suppliers (IEC/TR 62258-4:2007)

Halbleiter-Chip-Erzeugnisse - Teil 4: Fragebogen für Chip-Anwender und -Lieferanten (IEC/TR 62258-4:2007)

**ITeH STANDARD PREVIEW**

Produits a puce de semi-conducteur - Partie 4: Questionnaire pour les utilisateurs et les fournisseurs de puces (IEC/TR 62258-4:2007)

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**Ta slovenski standard je istoveten z: CLC/TR 62258-4:2007**

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**ICS:**

|           |                                     |                                       |
|-----------|-------------------------------------|---------------------------------------|
| 31.080.99 | Drugi polprevodniški elementi       | Other semiconductor devices           |
| 31.200    | Integrirana vezja, mikroelektronika | Integrated circuits. Microelectronics |

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**en,de**

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English version

**Semiconductor die products -  
Part 4: Questionnaire for die users and suppliers  
(IEC/TR 62258-4:2007)**

Produits à puce de semi-conducteur -  
Partie 4: Questionnaire  
pour les utilisateurs  
et les fournisseurs de puces  
(CEI/TR 62258-4:2007)

Halbleiter-Chip-Erzeugnisse -  
Teil 4: Fragebogen für Chip-Anwender  
und -Lieferanten  
(IEC/TR 62258-4:2007)

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This Technical Report was approved by CENELEC on 2007-09-01.

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**CENELEC**

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Central Secretariat: rue de Stassart 35, B - 1050 Brussels**

## Foreword

The text of document 47/1884/DTR, future edition 1 of IEC/TR 62258-4, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC Parallel Unique Acceptance Procedure and was approved by CENELEC as CLC/TR 62258-4 on 2007-09-01.

Annex ZA has been added by CENELEC.

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## Endorsement notice

The text of the Technical Report IEC/TR 62258-4:2007 was approved by CENELEC as a Technical Report without any modification.

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**Annex ZA**  
(normative)

**Normative references to international publications  
with their corresponding European publications**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

| <u>Publication</u> | <u>Year</u> | <u>Title</u>  | <u>EN/HD</u> | <u>Year</u> |
|--------------------|-------------|---|--------------|-------------|
| IEC 60050          | Series      | International Electrotechnical Vocabulary                                       | –            | –           |
| IEC 62258-1        | 2005        | Semiconductor die products -<br>Part 1: Requirements for procurement and<br>use | EN 62258-1   | 2005        |
| IEC 62258-2        | 2005        | Semiconductor die products -<br>Part 2: Exchange data formats                   | EN 62258-2   | 2005        |

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# TECHNICAL REPORT

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Semiconductor die products – **STANDARD PREVIEW**  
Part 4: Questionnaire for die users and suppliers  
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INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

PRICE CODE

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## SEMICONDUCTOR DIE PRODUCTS –

## Part 4: Questionnaire for die users and suppliers

## FOREWORD

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The main task of IEC technical committees is to prepare International Standards. However, a technical committee may propose the publication of a technical report when it has collected data of a different kind from that which is normally published as an International Standard, for example "state of the art".

IEC 62258-4, which is a technical report, has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this technical report is based on the following documents:

|               |                  |
|---------------|------------------|
| Enquiry draft | Report on voting |
| 47/1884/DTR   | 47/1909/RVC      |

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The list of all the parts of IEC 62258, under the general title *Semiconductor die products*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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## INTRODUCTION

This technical report is based on the work carried out in the ESPRIT 4th Framework Project GOODDIE which resulted in the publication of the ES 59008 series of European specifications. Organizations that helped prepare this document included the ESPRIT ENCAST and ENCASIT projects, the Die Products Consortium, JEITA, JEDEC and ZVEI.

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